

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV704345DBVT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV704345DBVT	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DBV 5	2.9x1.6x1.45	18.5

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.025002	100	1000000	0.13526	1353
Sub-Total			0.025002	100	1000000	0.13526	1353
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.09184	80	800000	0.496851	4969
Thermoplastics	Epoxy	85954-11-6	0.02296	20	200000	0.124213	1242
Sub-Total			0.1148	100	1000000	0.621063	6211
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	6.041125	97.4375	974375	32.682232	326822
Copper and Its Alloys	Iron	7439-89-6	0.1457	2.35	23500	0.788231	7882
Copper and Its Alloys	Phosphorus	7723-14-0	0.005115	0.0825	825	0.027672	277
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00031	0.005	50	0.001677	17
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00775	0.125	1250	0.041927	419
Sub-Total			6.2	100	1000000	33.541739	335417
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.114144	95.12	951200	0.617514	6175
Precious Metals	Gold	7440-57-5	0.000936	0.78	7800	0.005064	51
Precious Metals	Palladium	7440-05-3	0.00492	4.1	41000	0.026617	266
Sub-Total			0.12	100	1000000	0.649195	6492
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.126948	85.999999	860000	54.786363	547864
Other Plastics and Rubber	Carbon Black	1333-86-4	0.058878	0.500003	5000	0.318528	3185
Thermoplastics	Epoxy	85954-11-6	1.589695	13.499997	135000	8.600183	86002
Sub-Total			11.775521	100	1000000	63.705074	637051
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.249109	100	1000000	1.347669	13477
Sub-Total			0.249109	100	1000000	1.347669	13477
Total			18.484432			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.